

Publication

EP 0563374 A4 19940223

Application

EP 92924135 A 19921023

Priority

US 78097791 A 19911023

Abstract (en)

[origin: WO9308668A1] A dual plate heater (2) provides two parallel temperature self-regulating heater plates (6, 8) or wire mesh comprising ferromagnetic material with one or more electrically energized coils (4) parallel to and located between the heater plates (6, 8) which coil(s) (4) when energized by a constant current (14) or by an otherwise controlled current heat the plates to their Curie temperature or temperatures. The coil may be a flat spiral of thin conductive (copper) wire (4) embedded in a thin layer of a heat conductive, electrically non-conductive material (14) between said plates whereby heat energy generated in the coil is supplied to the heater plates (6, 8). The dual plate heater (2) may be employed to heat plastic pipes (Fig. 14) to their butt welding temperatures after which the heater is removed and the ends of the pipes to be joined are brought into contact under pressure. The dual plate heaters may also be employed in other arrangements such as shelves (Fig. 15) in a dispensing machine.

IPC 1-7

H05B 6/12

IPC 8 full level

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CPC (source: EP)

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Citation (search report)

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- [A] EP 0250094 A1 19871223 - METCAL INC [US]
- [A] R. B. JABLONSKI: "INDUCTIVE HEATING OF FLUIDS", IBM TECHNICAL DISCLOSURE BULLETIN, vol. 14, no. 10, 1 March 1972 (1972-03-01), NEW YORK.;US, pages 3174
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